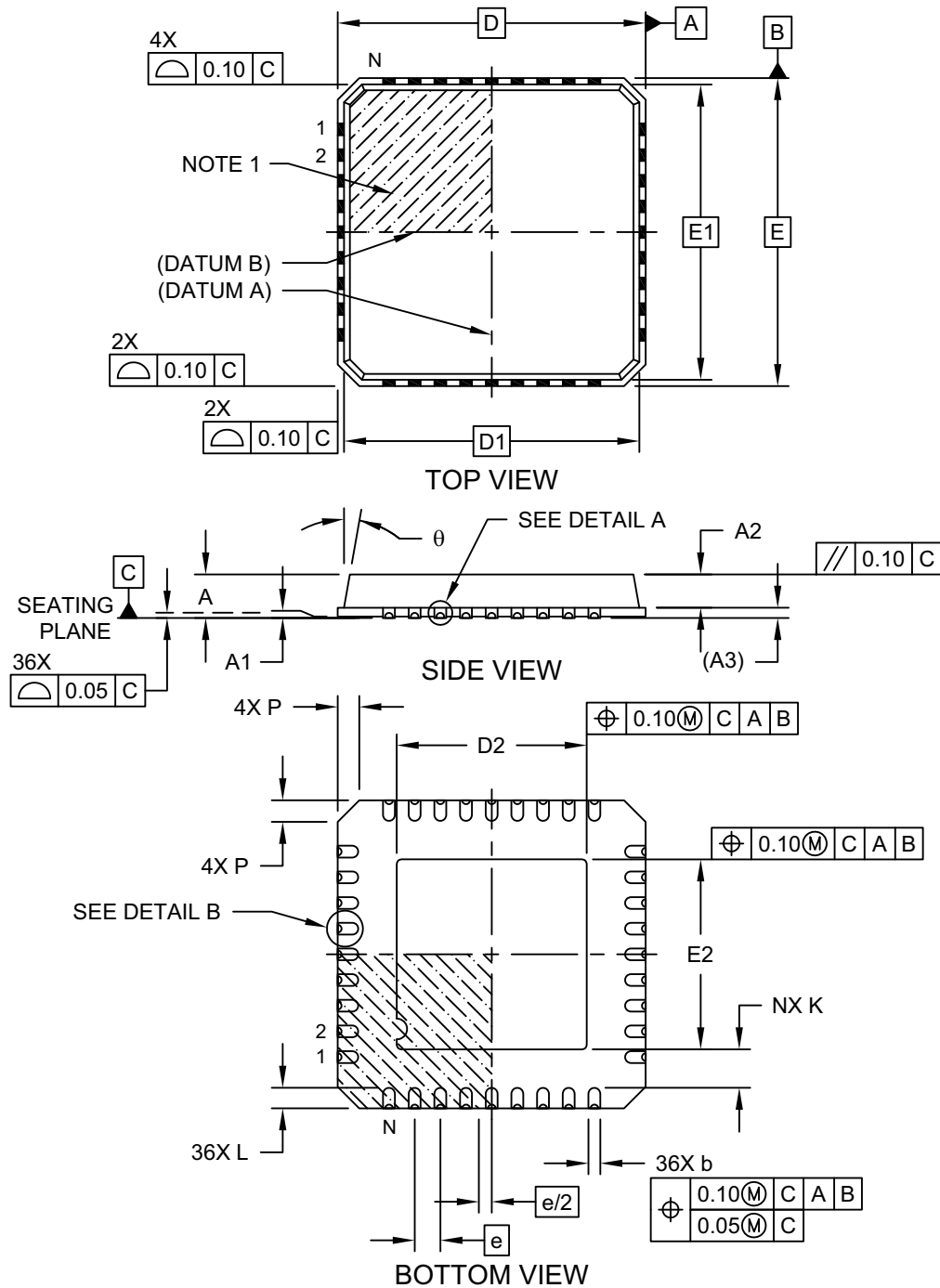


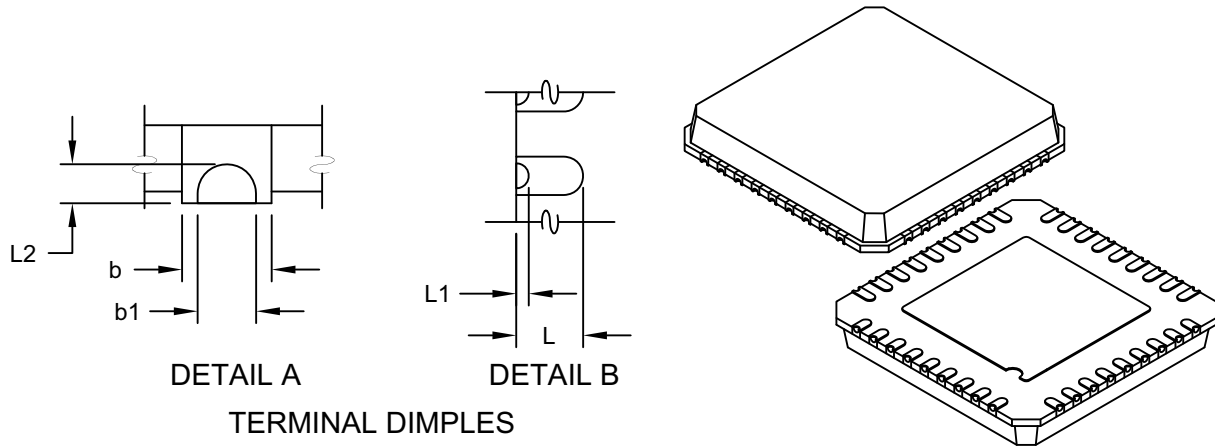
**36-Lead Plastic Quad Flat, No Lead Package (4E) - 6x6 mm Body [QFN]
With 3.7x3.7 mm Exposed Pad; Punch Singulated, 0.40 mm Dimpled Terminals**

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



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TERMINAL DIMPLES

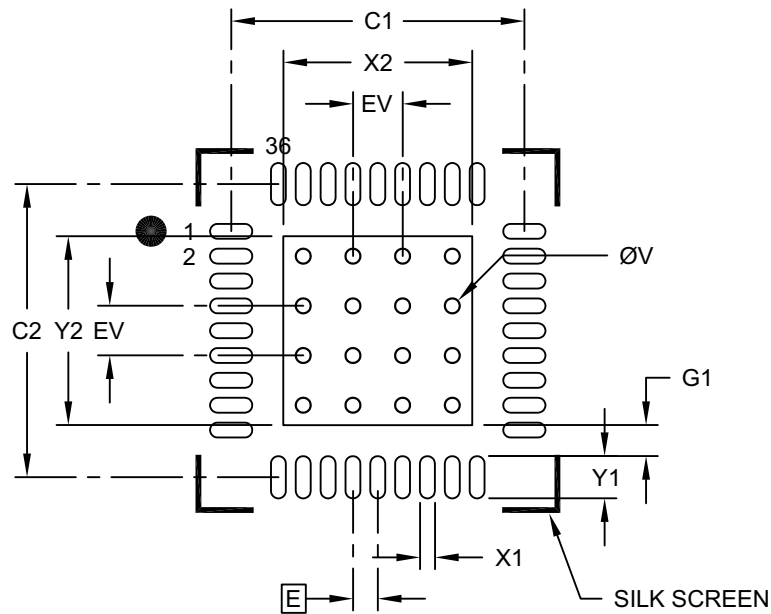
Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Terminals	N	36		
Pitch	e	0.50 BSC		
Overall Height	A	0.80	0.85	0.90
Standoff	A1	0.00	0.01	0.05
Mold Cap Height	A2	0.60	0.65	0.70
Terminal Thickness	(A3)	0.20 REF		
Overall Width	E	6.00 BSC		
Molded Top Width	E1	5.75 BSC		
Exposed Pad Width	E2	3.60	3.70	3.80
Overall Length	D	6.00 BSC		
Molded Top Length	D1	5.75 BSC		
Exposed Pad Length	D2	3.60	3.70	3.80
Corner Chamfer	P	0.24	0.42	0.60
Terminal Width	b	0.20	0.25	0.30
Terminal Dimple Width	b1	0.10	0.15	0.20
Terminal Length	L	0.30	0.40	0.50
Terminal Dimple Length (side)	L1	0.05	0.15	0.25
Terminal Dimple Length (bottom)	L2	0.05	0.10	0.15
Terminal-to-Exposed-Pad	K	0.20	-	-
Mold Draft Angle	θ	0°	-	12°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is punch singulated
3. Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

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RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Optional Center Pad Width	X2			3.80
Optional Center Pad Length	Y2			3.80
Contact Pad Spacing	C1		5.90	
Contact Pad Spacing	C2		5.90	
Contact Pad Width (X36)	X1			0.30
Contact Pad Length (X36)	Y1			0.85
Contact Pad to Center Pad (X32)	G1	0.20		
Thermal Via Diameter	V		0.30	
Thermal Via Pitch	EV		1.00	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2241A